

# Bringing RF Tunability to Mobile Communications Markets

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- ⚡ Brief Introduction to Peregrine Semiconductor and UltraCMOS™
- ⚡ Tunability Defined
- ⚡ Antenna Frequency & Impedance Tuning
- ⚡ Amplifier Multi-Mode Operation
- ⚡ The Power of CMOS Integration
  - Power Control
  - Digital, Analog, RF
- ⚡ Conclusion

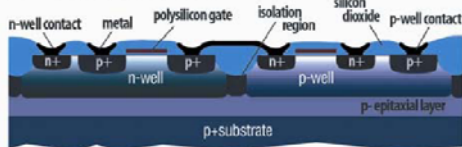
# UltraCMOS™ Integrates Best In Class Performance



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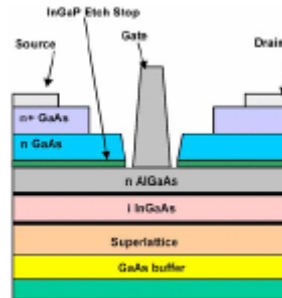
## Bulk CMOS

### Bulk CMOS Process



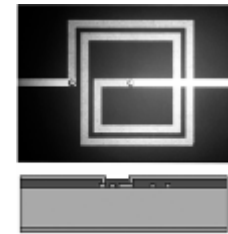
- Monolithic Integration
  - Manufacturable
  - Transferrable
  - Repeatable
  - Scalable

## Gallium Arsenide



- RF Power Applications
  - Good linearity
  - High mobility
  - High power handling
  - Good isolation

## Integrated Passive Device



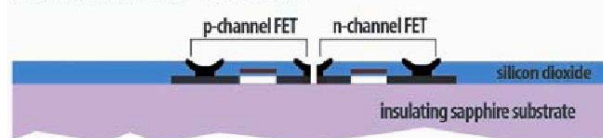
■ LCP ■ BCB  
■ Metal Conductor

- Passive Integration
  - Miniaturized passive blocks
  - Minimized parasitics
  - Lithographic interconnect

## UltraCMOS™

- All positive attributes of CMOS
- All positive attributes of GaAs
- All positive attributes of IPD
- Additional Unique Properties

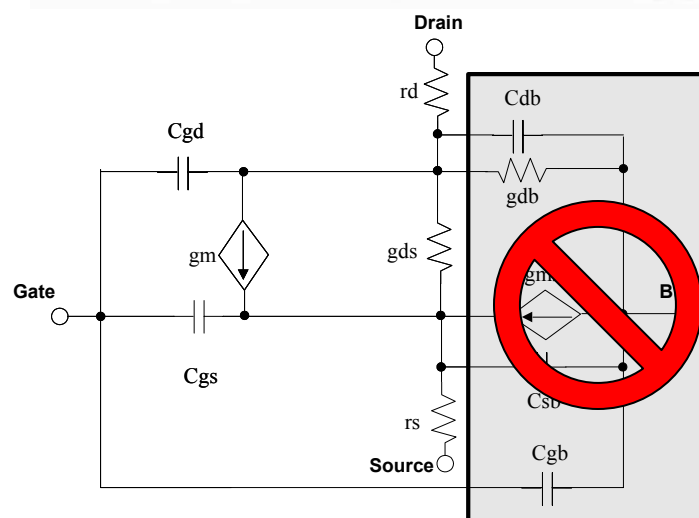
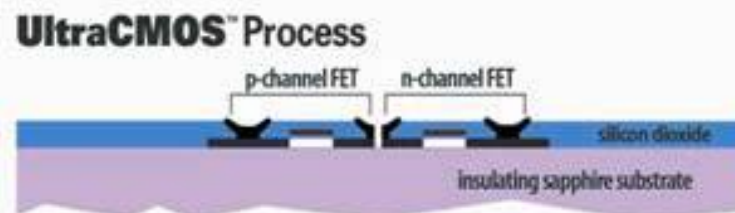
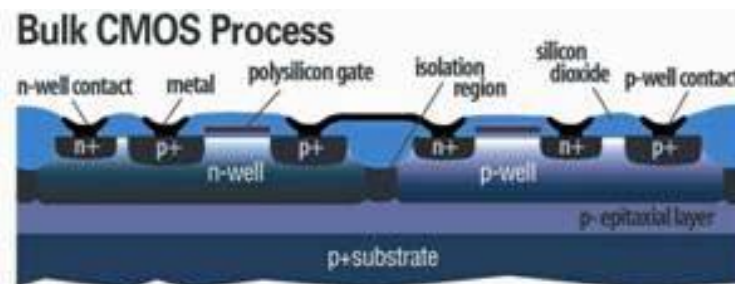
### UltraCMOS™ Process



- + Broadband Linearity
- + Unprecedented Isolation
- + High ESD Handling
- + Onboard Memory - EEPROM

/// The sapphire substrate eliminates the bulk parasitics!

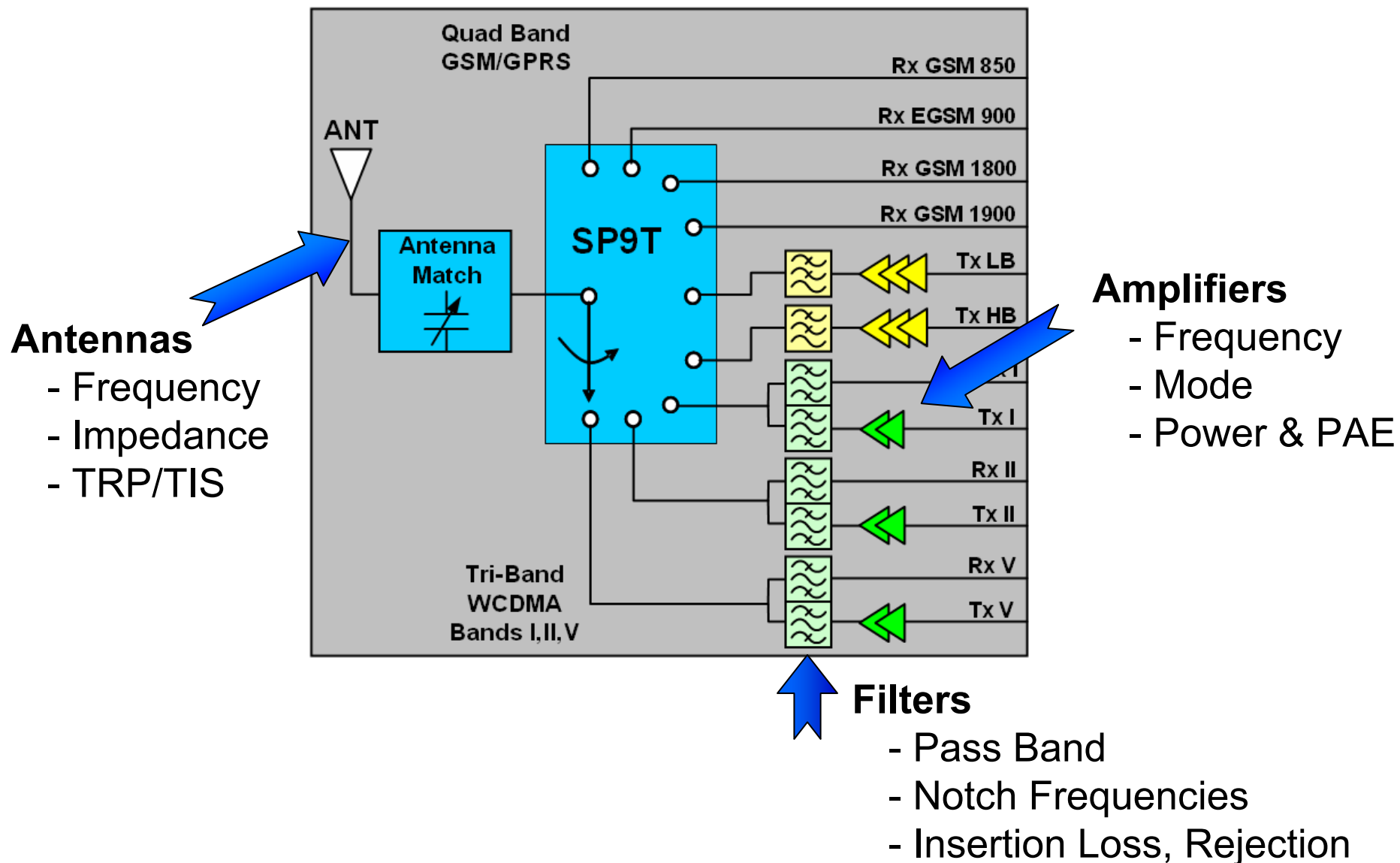
- **Fast** devices
- **Ultra low power** loss
- Excellent **linearity**
- Unprecedented **isolation**
- Ability to integrate **high Q passives**
- Ability to integrate multiple **RF / mixed signal / digital** functions monolithically



# Tunability Defined – 3G Handset Architecture



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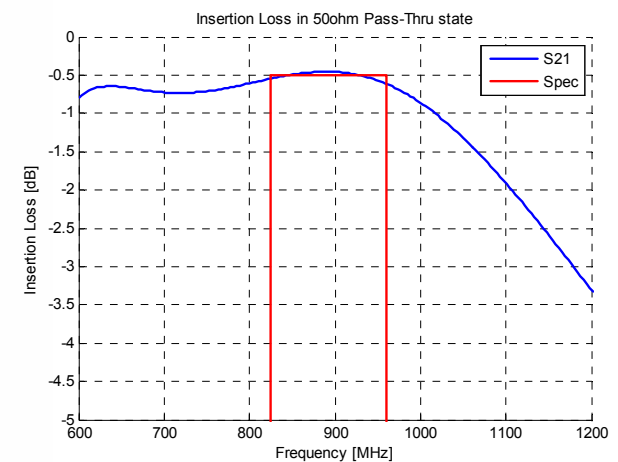
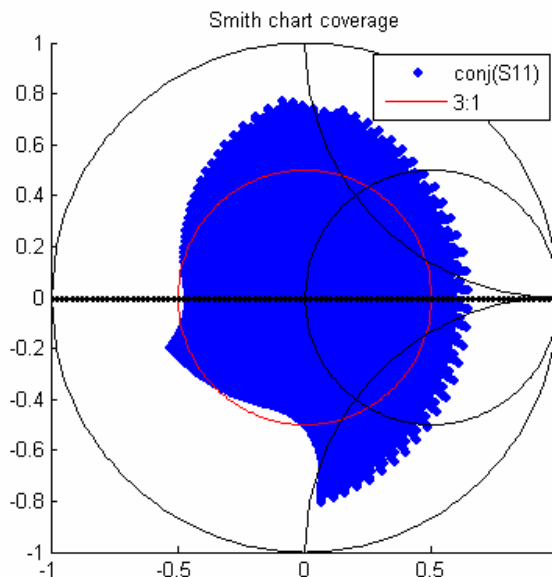
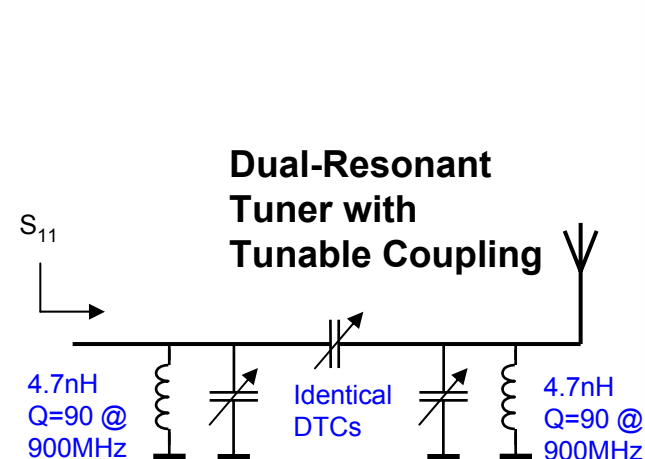
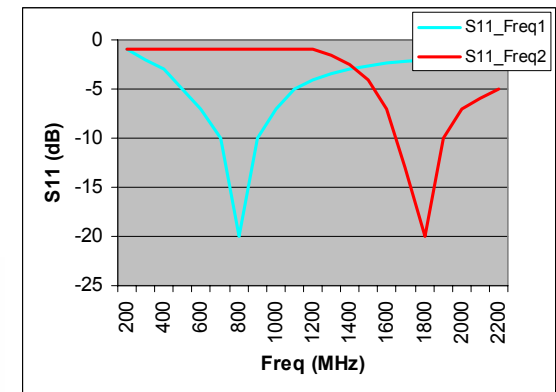
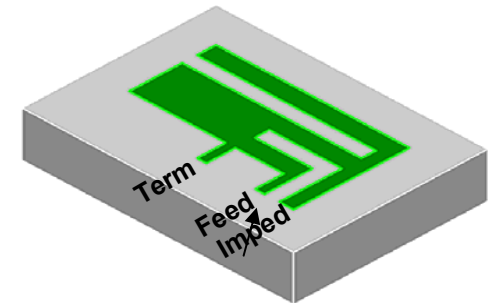


- ⌘ The Number of Handset Frequency Bands continues to increase
  - Moving from 2G Quad Band to 3G/4G 7-12 band Smart Phones
  - Drives the complexity and increases the number of discrete, fixed frequency components
- ⌘ Tunability helps reduce the total Bill of Material
  - Multiple Antennas, PAs, Filters are replaced with fewer, tunable elements
- ⌘ Reduce total board area with fewer components
- ⌘ Tunability leads to improved communication link performance
  - Improved TRP & TIS leads to lower BER, fewer dropped calls
- ⌘ Improve battery talk time
  - Antenna impedance matching is the most straightforward means to improve TRP by >3dB
    - ◄ The PA Power savings drops directly to the talk time “bottom line”
  - Improve Tx efficiency level over entire PDF

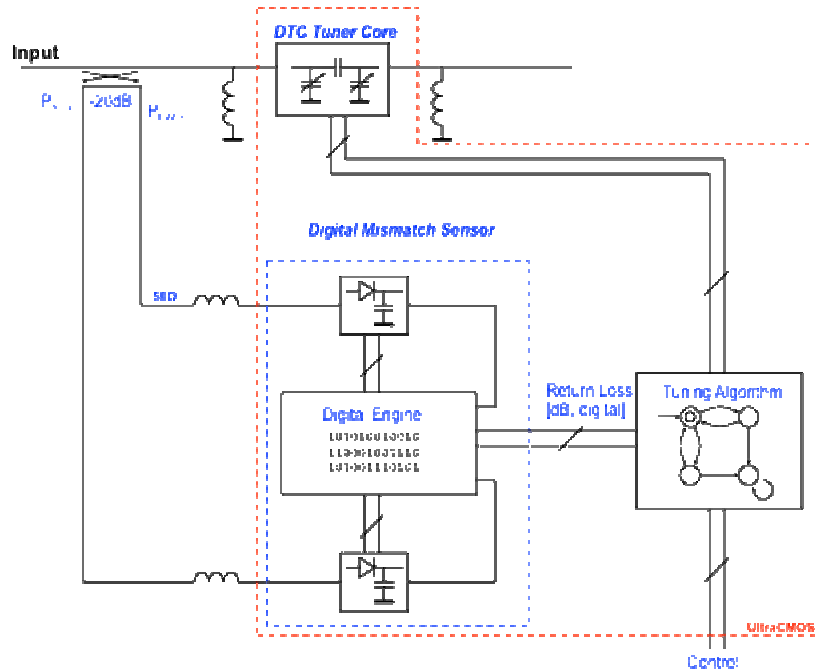
## Frequency Tuning of a PIFA Antenna with an Variable Loading Impedance

- Single antenna with minimal volumetric size can address multiple bands

## Impedance Matching of Antenna to address EM Proximity Effects







## Pro's and Con's

- /// Improves static and dynamic mismatch loss
- /// Complex system design
- /// Requires close co-operation with handset/network provider to implement solution

## Implementation and Control

- /// RF Front-end mismatch tuning device controlled by a closed loop mismatch sensing device and tuning algorithm
- /// The sensing and tuning algorithm can be implemented several ways
  - /// Fully autonomous subsystem – turn it on and it tunes
  - /// Controlled by BB/DSR core processor chip

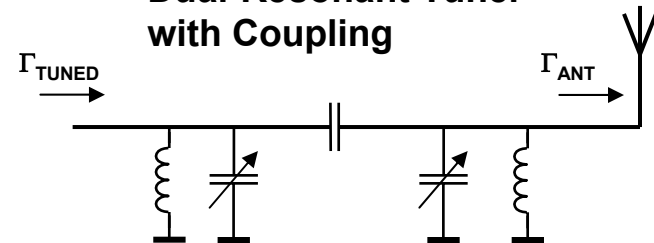


With Tunability come new design challenges

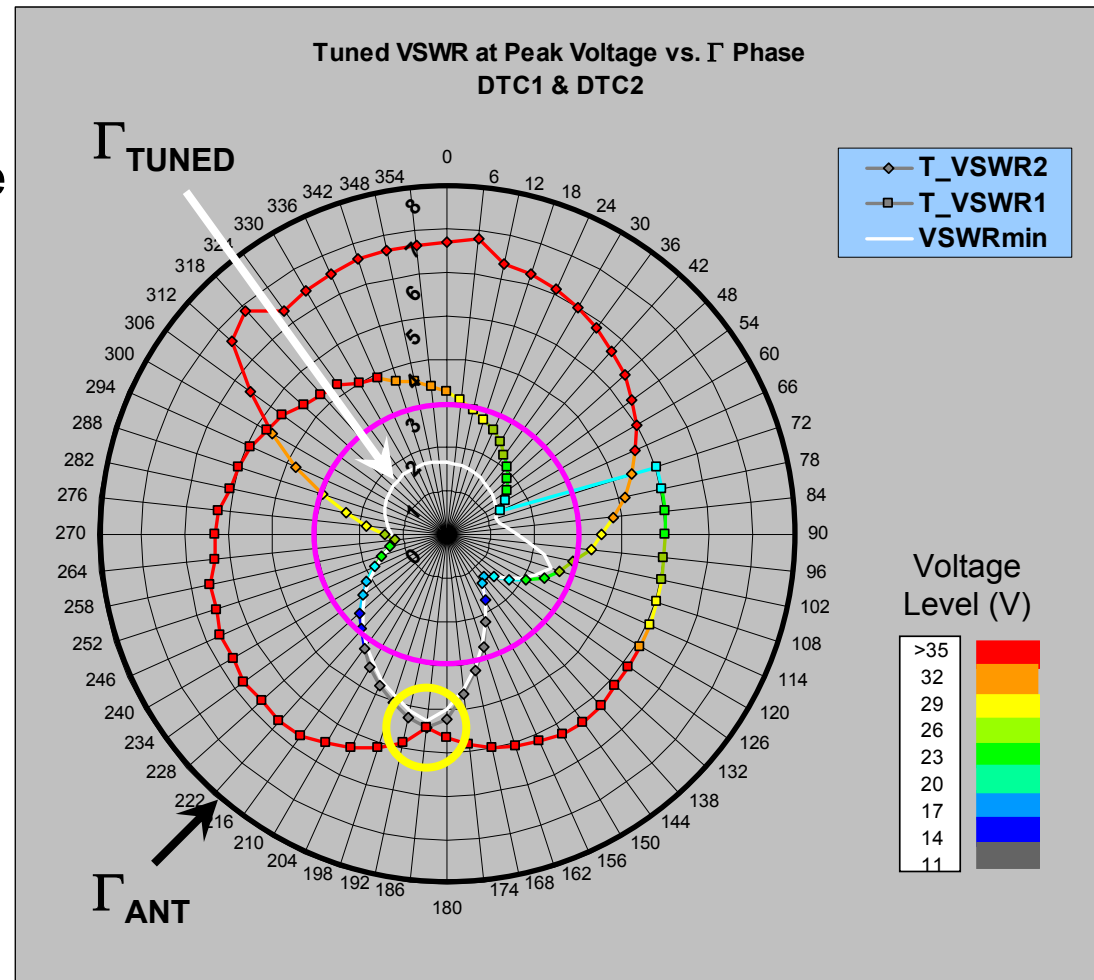
- e.g. Avoid High Voltage conditions over impedance tuning range

- ◀ Linearity
- ◀ Reliability

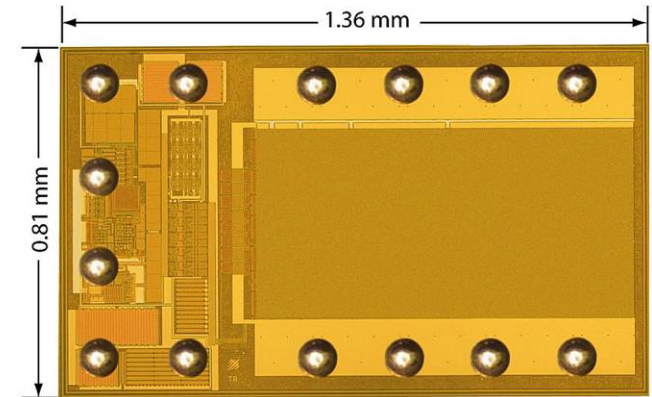
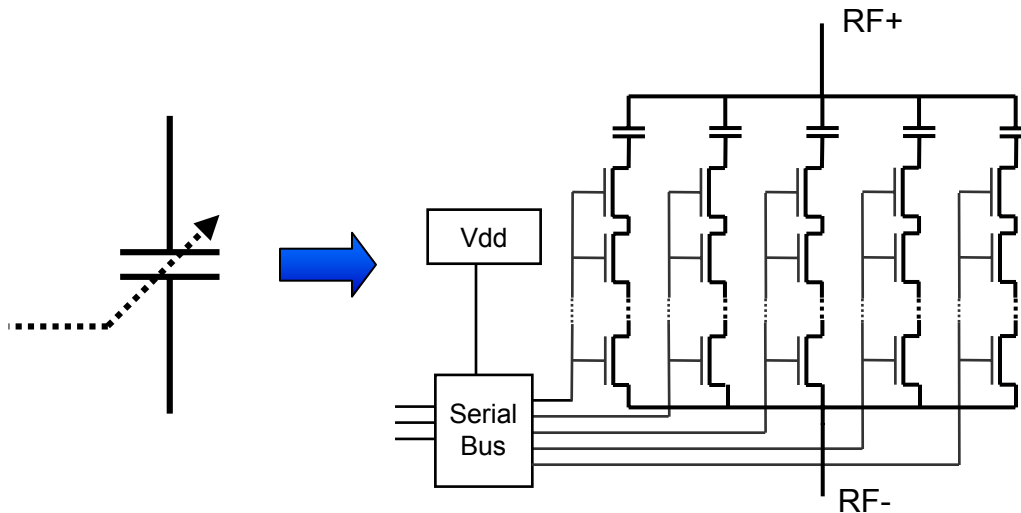
Dual-Resonant Tuner with Coupling



8:1 Antenna Impedance  $\Gamma_{ANT}$  Matched to  $\Gamma_{TUNED}$



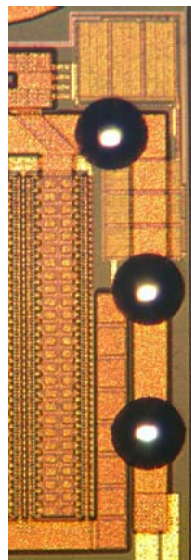
+34dBm  $P_{INC}$  @ 900MHz



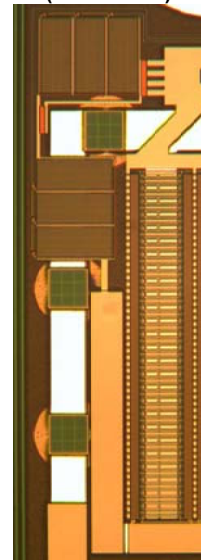
## Device Features

- /// Single monolithic die
- /// Solid state implementation
- /// Direct connect to  $V_{BAT}$
- /// Simple serial control interface
- /// Proven UltraCMOS™ process
  - /// >700M devices manufactured
- /// DTC can be directly integrated within more complex RFICs

Front Side  
DTC+PA Final

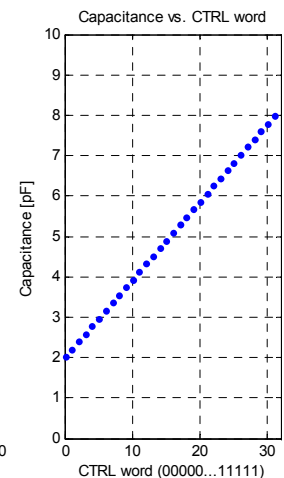
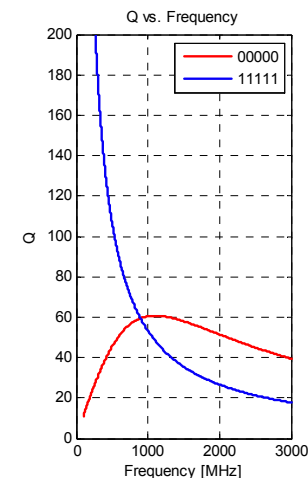


Back Side  
(Thru Wafer)



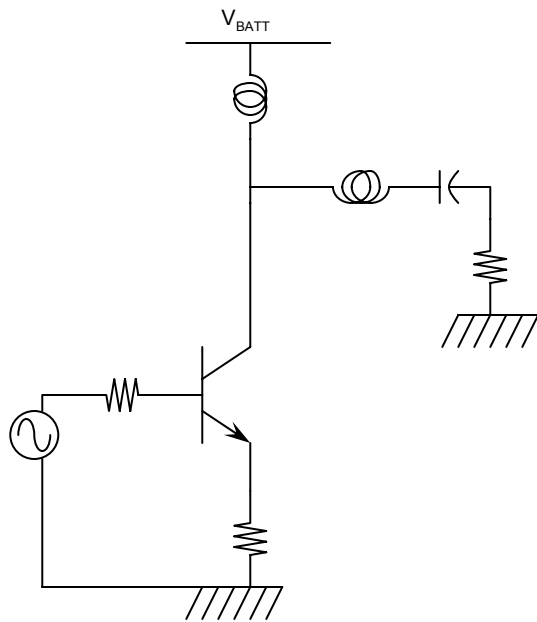
## Performance Attributes

- /// Tuning range of 4:1
- /// Capacitor range 2pF to 8pF
- /// Typical Q = 60 @ 1GHz

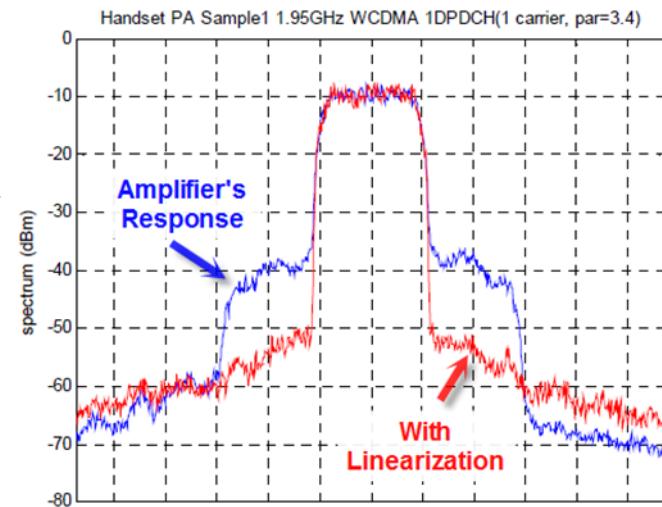
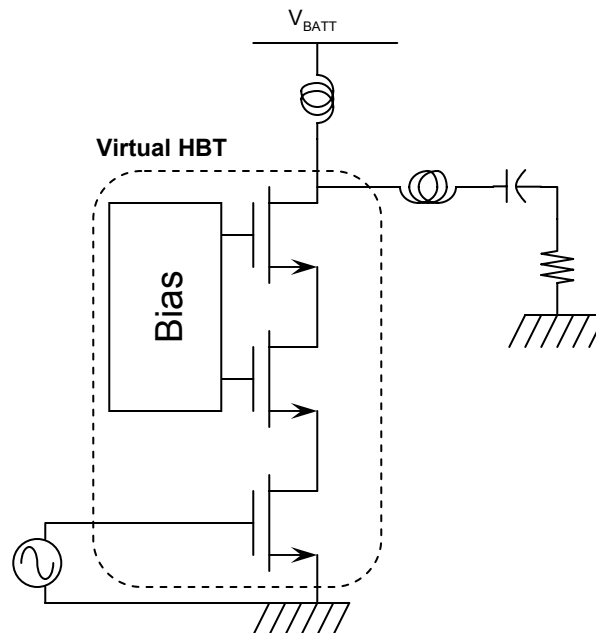


- Using device stacking, a virtual high-voltage three-terminal device can be realized
  - Can be operated in either linear or switched mode
  - Complex control and linearization schemes can be implemented
    - Analog, Digital linearization/pre-distortion techniques

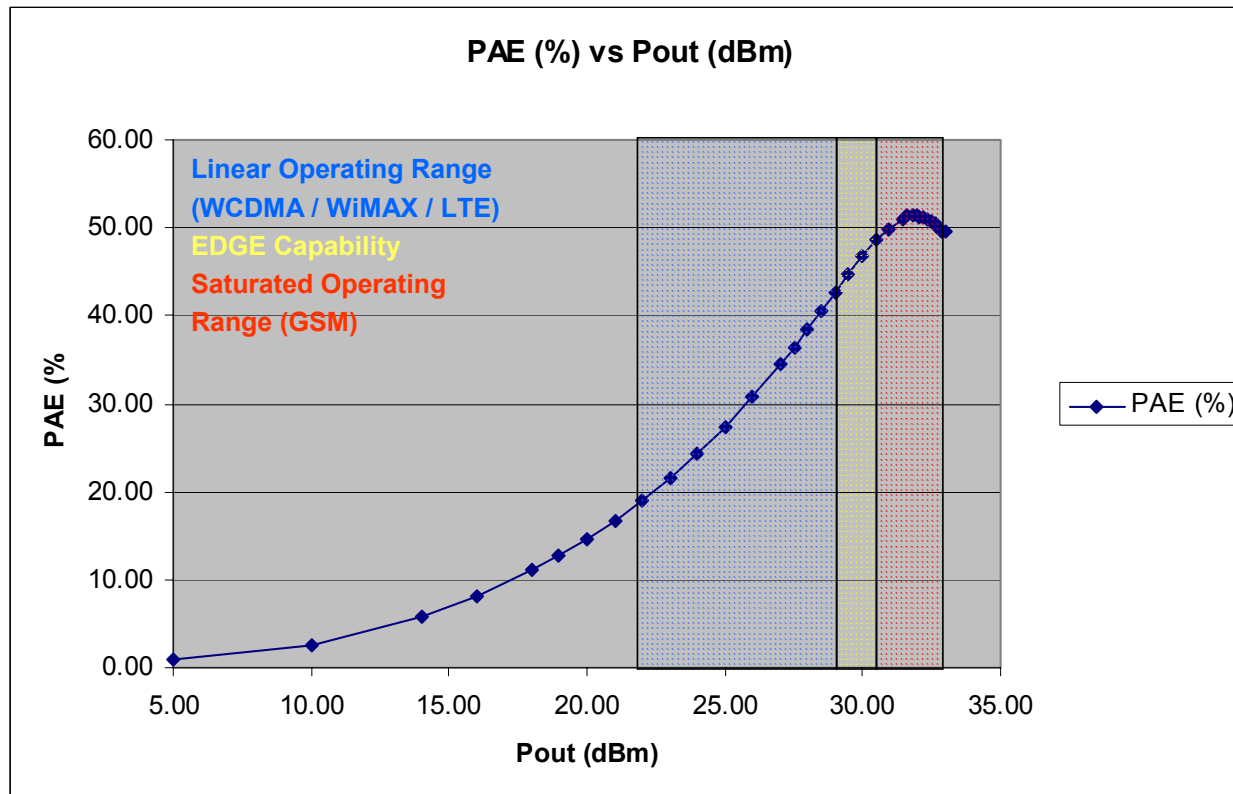
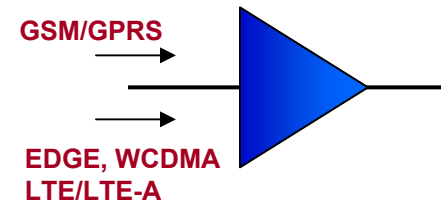
## HBT PA Implementation



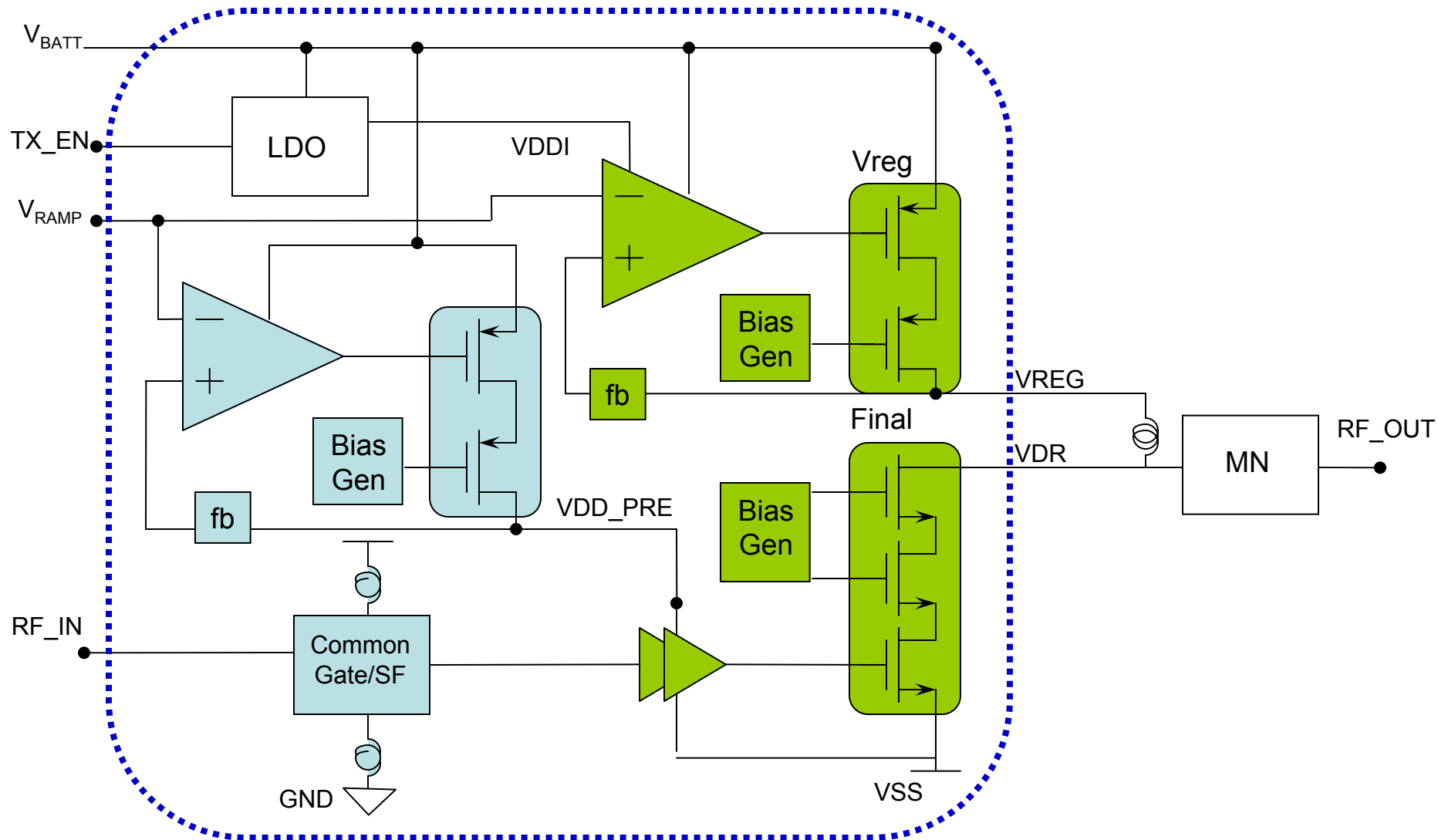
## CMOS PA Implementation



- /// Critical to reducing the number of power Amplifiers is Multi-Mode Operation from a single amplifier
  - Constant Envelope versus high Peak-to-Avg Ratios (PAR)
- /// Common Final Amplifier Stage Performance
  - Pout & PAE performance maintained across multiple access schemes

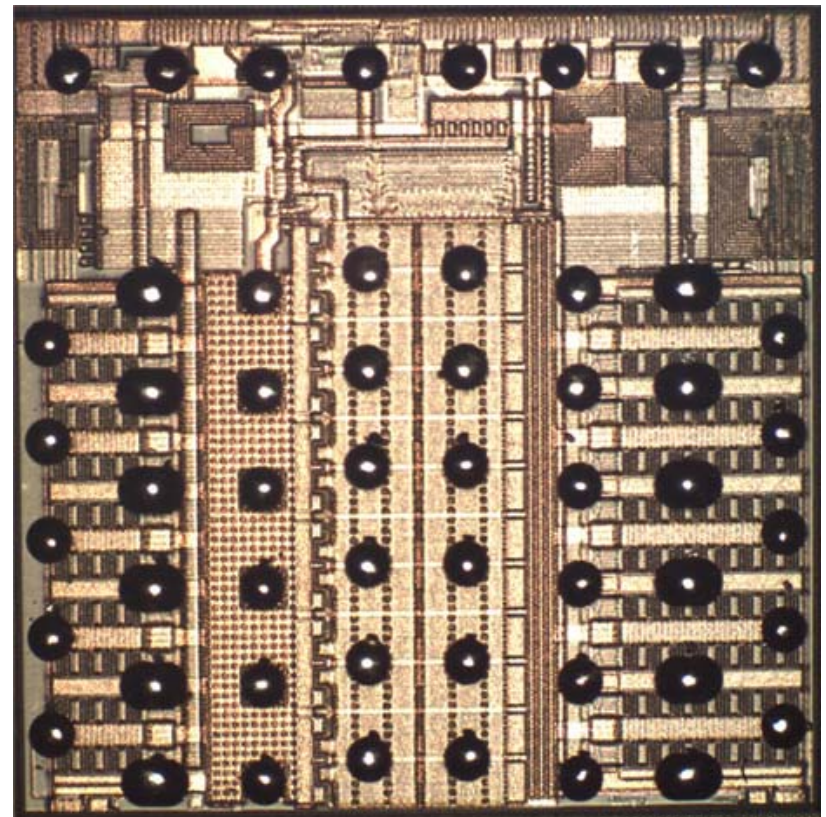
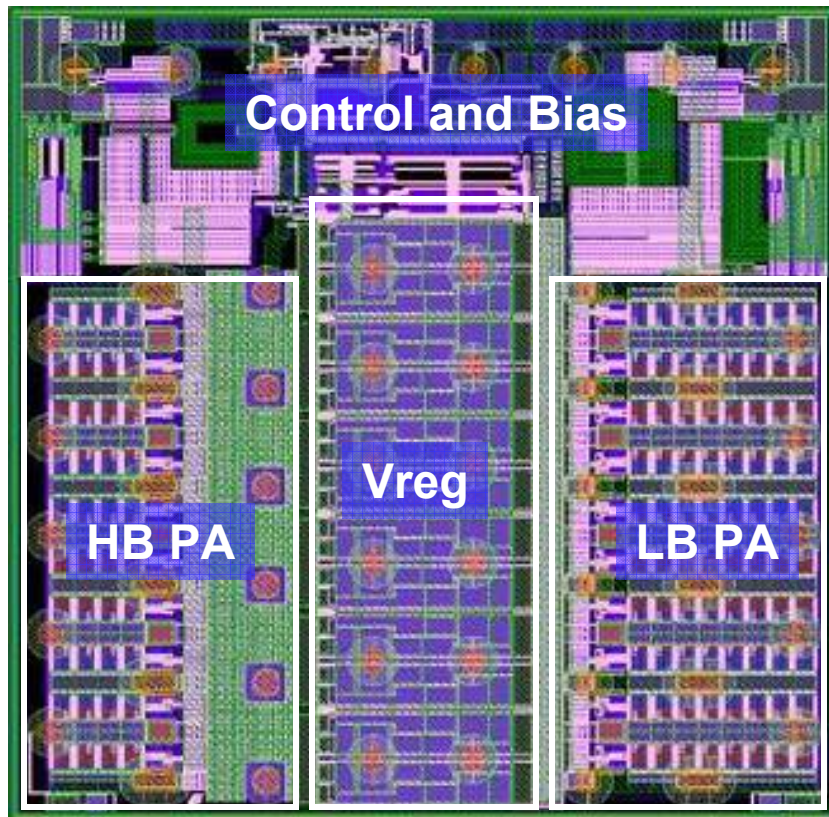


# Complete Integration of GSM PA with Controller





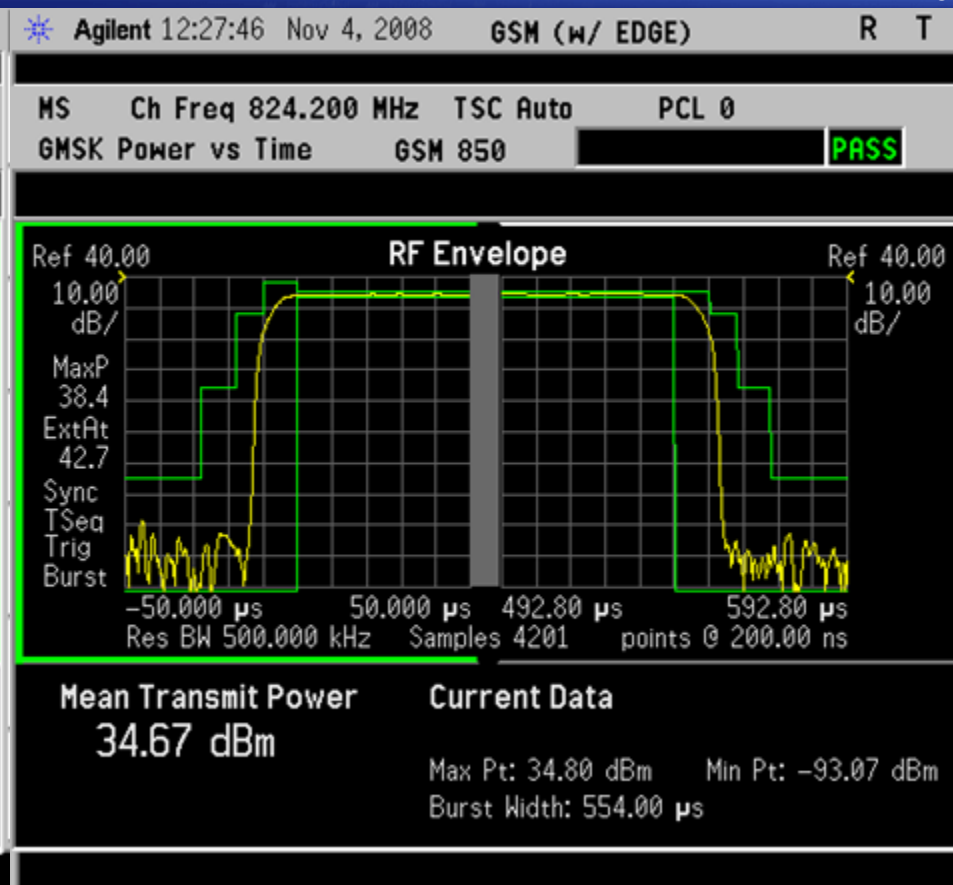
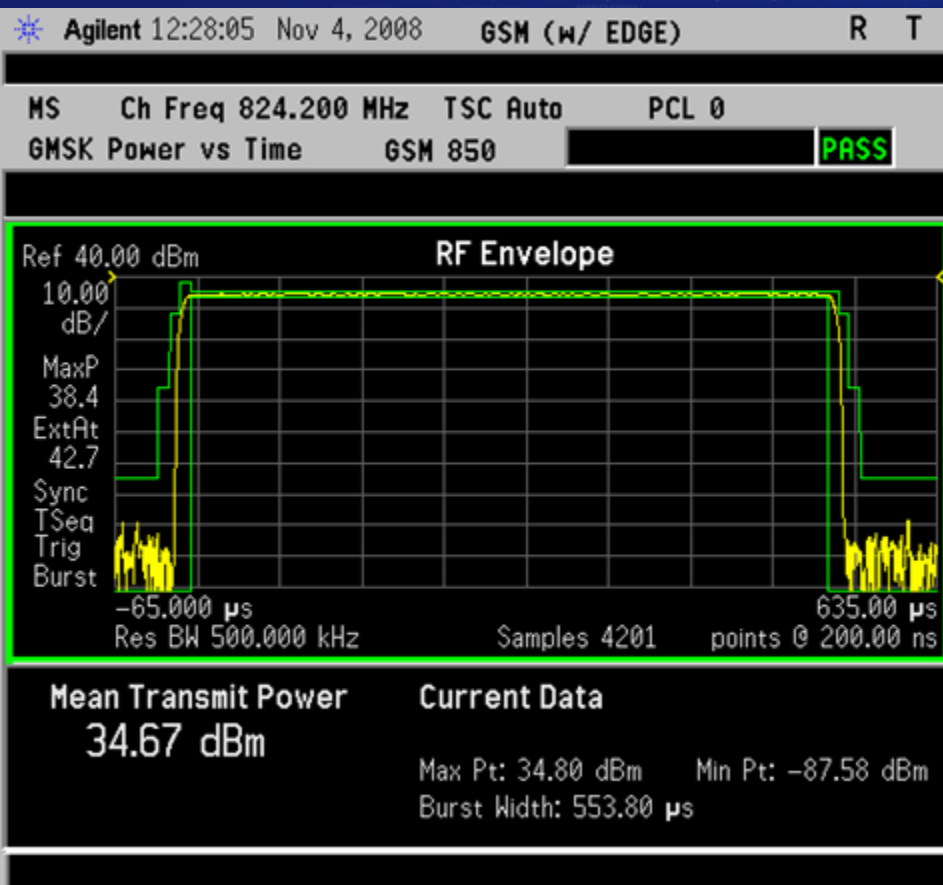
- ⌘ Monolithic Integration of the GSM APC function
- ⌘ Rugged into any load condition at max power



# GSM 850 – Power vs. Time @ 3 V Vbatt



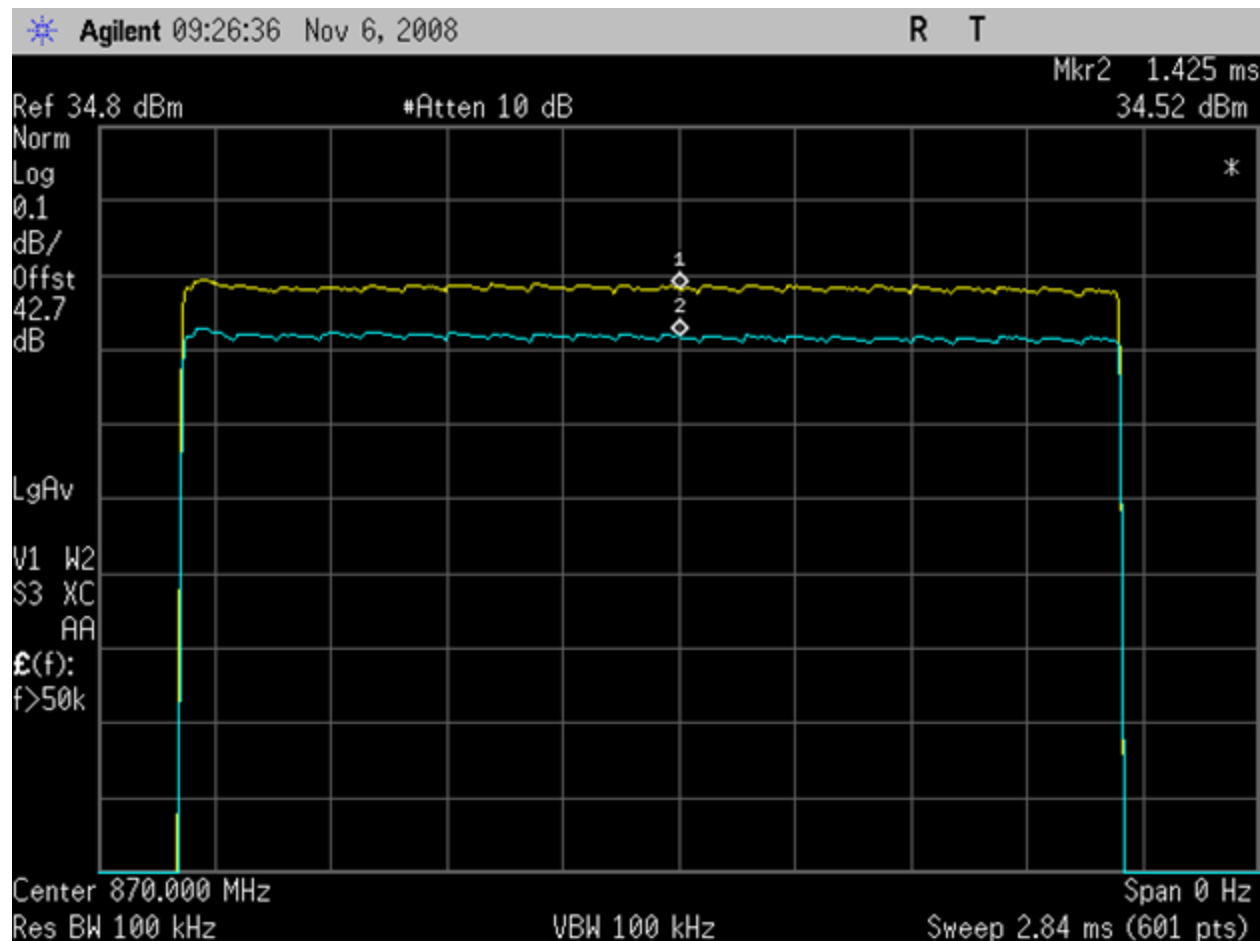
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- Large power control range > 75dB
  - Tx/Rx Switch doesn't have to be sequenced to meet the time mask
- Well behaved analog power control
- Very repeatable results – multiple parts/multiple wafers
  - Over frequency and  $V_{BATT}$  range



# GPRS Class 12 (50%) Operation



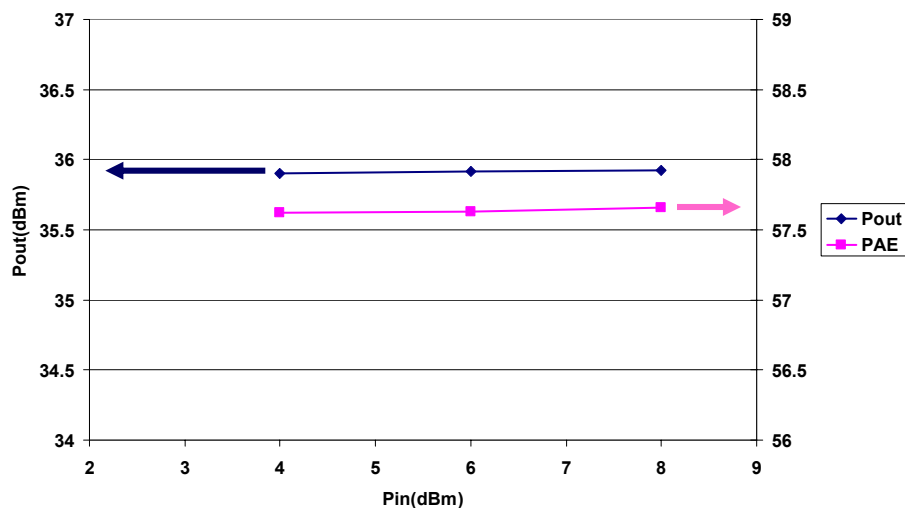
Marker1 (Yellow Trace) @ Start = 34.58 dBm

Marker2 (Blue Trace) @ 5 minutes Later = 34.52 dBm

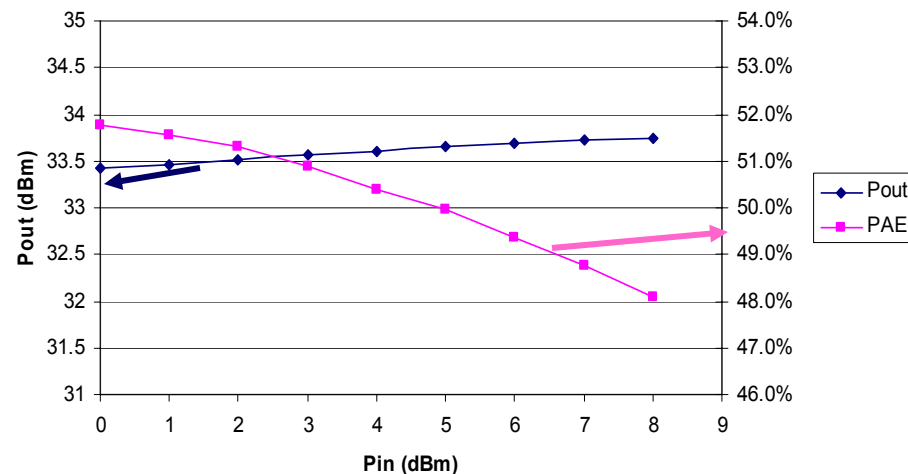
Delta = .06 dB

# Output Power & Total Efficiency vs. Pin

Low Band Pout, PAE vs. Pin



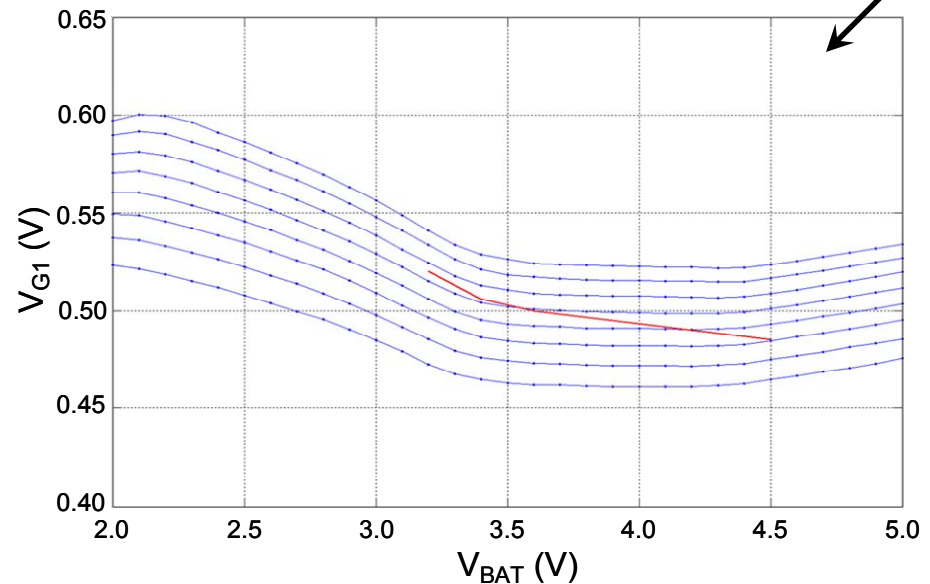
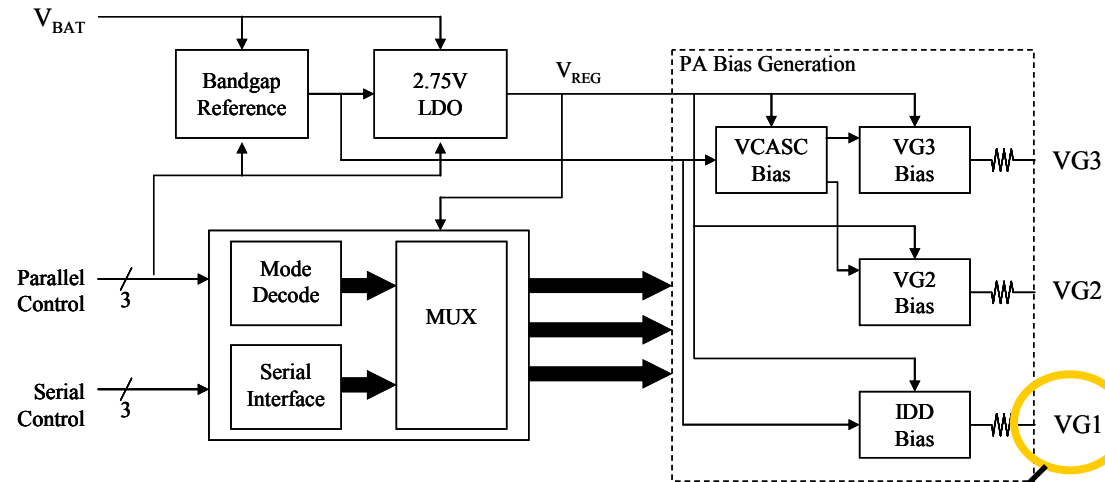
High Band Pout, PAE vs. Pin



Measurement Conditions: Freq.=880 MHz, 1780MHz  
 $V_{BATT}=3.5V$ ,  $V_{RAMP}=1.7V$

- Outstanding Efficiency (best CMOS results, competitive with GaAs)
- Plenty of Output Power
- Pout independent of Pin
- Low Pout dependence on Temperature and  $V_{BATT}$

- Provides optimum linearity performance
  - ACLR, IP3
- Minimizes performance sensitivity to Process,  $V_{BATT}$ , and Temp Variations
- Relies upon proven CMOS Analog & Digital design concepts to optimize operating points based upon PVT



- ⚡ Peregrine UltraCMOS has demonstrated tunability that addresses:
  - Frequency band switching
  - Impedance matching
  - Output power optimization
  - Access scheme/mode of operation
  - Tuning for environmental effects
    - ◀ Proximity effects
    - ◀ Temp, Battery
- ⚡ Integration of high performance RF with Digital and Analog circuitry is paramount to tunability
  - $Q_{cap} > 60$ ,  $Q_{ind} > 30$  for 1-2GHz
  - Ron-Coff Device FOM is continuing down CMOS scaling curve
    - ◀  $375 \rightarrow 275 \rightarrow 225$  fS (1 Ohm-mm, 275fF/mm)
    - ◀  $F_{MAX}$  50GHz  $\rightarrow$  100GHz